**Minutes – 200818**

**Present: HH, SB, TJ, IT, SW**

**Apologies: JT, AG, PS,**

**Strip modules**

Same as last week.

SW has SBS account. (email Steve Haywood/ GillBirch)

*Tooling review is ongoing. So far no comments. Discussion with ankush about 12 module chuck thing. Sven thinks it may not work. AG did work on new pcb – but now on holiday. Sven to build the new module this week. Alibaba measurement of irradiated sensors (LSS qualification. Deadline is for market survey.)*

*Sent 5 cm sensors we cannot readout using Alibaba. Sven to send back.*

*Clean room closed Thursday- Monday.*

**Strip Mechanics**

Waiting for DS to do stave core assembly. PS has drawing of vacuum jig. He can work on it for 2 days, whilst he at CERN. He has quote for material. TJ to send to Gill Birch to get ordered. TJ to speak to Dan/Mark to find when big machine available from LHcb.

Hamish has questions, DS answered. Anxious to start building.

**Pixel modules**

Designed cern pixel 8, cern pixel 9(quads). Both made for RD53a. plans for RD53b not known yet. Micron on holiday. RD53b is twice the size.

Design will be ready by 10th sep. estimated turn over 6 months.

Want to start hybrid design. Rigid board for doubles. Prototype flex for quad. Taking issues of common hybrid in mind. They don’t want mounting frame. 4th major design is ring0 commitment. Going for mini-USB connector for ring 0. Just enough twisted pairs (has 6 twisted pair ).

Should get handling frame from Glasgow this week. Would be good to get interface card from Ilya this week. It would be good to tell people where we want the electrical modules. Also send the boards down to RAL.

Module production: we now have silicon (arrived Friday). Have been asked to measure planarity on the chip side. YG is here this week from lunchtime tomorrow. LB to do wire-bonding.

We must measure IV of silicon. Our testcard is also for IV measurements.

We only have 2 bent flexes. Need workshop to alter jig for clearance for bent tabs. Rubber press works very well.

50 micron is optimal thickness for strength.

Go over module assembly procedure tomorrow afternoon. Can we do a few more checks. Weigh things. Use dummies. Design a program for module production..

Afterwards, -> program YARR for FEI4. Timon has provided new firmware.

Q: will we be ready for irradiated module from birnimgham.

Testbox:

TJ has box, ductwork, heat exchanger has been screwed. Need to order American screws.

Next thing is to work out how to support handling frame. Use standard parts from Thorlabs. Large optical bread board. Parts arrive weds/thurs. TJ needs to sort out chiller. Q: can use small grant chiller.

**Pixel Mechanics**

Stalled whilst PS away.

TJ has emailed Danilo G. TJ to email outer barrel and inner pixel people, and cc Danilo.

Wednesday: milestones for pixel structures.

*Have quotes for CF – much more expensive that we originally though. We are now asking for cyanate ester*

*Do we really need the expensive one? We have experience through the face sheets.*

* *As PC to follow up.*

**AOB**

**HH-> get pizza night date.**

SW to sort travel documentation.